DCK PACKAGE (TOP VIEW)

в[

GND 🛚

SLOS424B - MARCH 1996 - REVISED FEBRUARY 2008

Π v<sub>cc</sub>

- Qualified for Automotive Applications
- Operating Range of 2 V to 5.5 V
- Max t<sub>pd</sub> of 6.5 ns at 5 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±8-mA Output Drive at 5 V
- Schmitt-Trigger Action at All Inputs Makes the Circuit Tolerant for Slower Input Rise and Fall Time
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## description/ordering information

The SN74AHC1G00 performs the Boolean function  $Y = \overline{A \bullet B}$  or  $Y = \overline{A} + \overline{B}$  in positive logic.

### ORDERING INFORMATION†

TA	PACKAGE	<b>‡</b>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	SN74AHC1G00QDCKRQ1	AAU

<sup>†</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

#### **FUNCTION TABLE**

INPU	JTS	OUTPUT
Α	В	Y
Н	Н	L
L	Χ	Н
Х	L	Н

## logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>‡</sup> Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Output voltage range, V <sub>O</sub> (see Note 1)	0.5 V to $V_{CC}$ + 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ )	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	252°C/W
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	V
		V <sub>CC</sub> = 2 V	1.5		
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
		V <sub>CC</sub> = 5.5 V	3.85		
		V <sub>CC</sub> = 2 V		0.5	
٧ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9	-l ' l
		V <sub>CC</sub> = 5.5 V		1.65	
VI	Input voltage				V
٧o	Output voltage		0	Vcc	V
		V <sub>CC</sub> = 2 V		-50	μΑ
loh	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	4
		$V_{CC} = 5 V \pm 0.5 V$		-8	mA
		V <sub>CC</sub> = 2 V		50	μΑ
lOL	Low-level output current	V <sub>CC</sub> = 3.3 V ± 0.3 V		4	
-		$V_{CC} = 5 V \pm 0.5 V$		8	mA
Δt/Δν		V <sub>CC</sub> = 3.3 V ± 0.3 V		100	0.7
	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		20	ns/V
T <sub>A</sub>	Operating free-air temperature				°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C TO 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
		2 V	1.9	2		1.9		
	I <sub>OH</sub> = -50 μA	3 V	2.9	3		2.9		
Vон		4.5 V	4.4	4.5		4.4		V
	I <sub>OH</sub> = -4 mA	3 V	2.58			2.48		
	I <sub>OH</sub> = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1	
VOL		4.5 V			0.1		0.1	
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.5	
	I <sub>OL</sub> = 8 mA	4.5 V			0.36		0.5	
IĮ	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1		10	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		2	10		10	pF

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	LOAD CAPACITANCE	T,	4 = 25°C	;	T <sub>A</sub> = -		UNIT									
	(INPUT)	(OUTPUT)	(001701)	(OUTPOT) CAPACITANG	CAPACITANCE	MIN	TYP	MAX	MIN	MAX								
tPLH	A = 1 D	V	0. 455		5.5	7.9	1	11.5										
t <sub>PHL</sub>	A or B	Y	Y	Ť	Ť	Ť	Ť	Ť	Ť	Y	Y C	Y C <sub>L</sub> = 15 pF	A 01 B 1 CL = 15 pr	5.5	7.9	1	11.5	ns
t <sub>PLH</sub>	A or B	V	C: - 50 pF		8	11.4	1	15	20									
tPHL	AUIB	Y	Y	Y	Y	T T	T T	OLD	C <sub>L</sub> = 50 pF		8	11.4	1	15	ns			

## switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

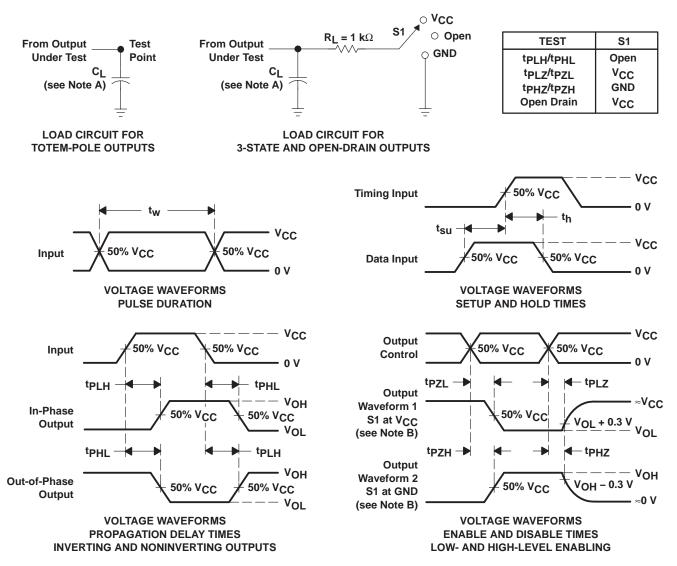
PARAMETER	FROM	TO (OUTPUT)	LOAD	T	դ = 25°C	;	T <sub>A</sub> = -		UNIT		
	(INPUT)	(OUTPUT)	JTPUT) CAPACITANCE	MIN	TYP	MAX	MIN	MAX			
tPLH	A or B Y	Y	0 45 5		3.7	5.5	1	8.5			
tPHL			C <sub>L</sub> = 15 pF		3.7	5.5	1	8.5	ns		
tPLH	A or B	V	C: - 50 pF		5.2	7.5	1	10.5	20		
tPHL		Y	Y	T T	C <sub>L</sub> = 50 pF		5.2	7.5	1	10.5	ns

## operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	9.5	pF



### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 3$  ns.  $t_f \leq 3$  ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







i.com 18-Sep-2008

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AHC1G00QDCKRQ1	ACTIVE	SC70	DCK	5	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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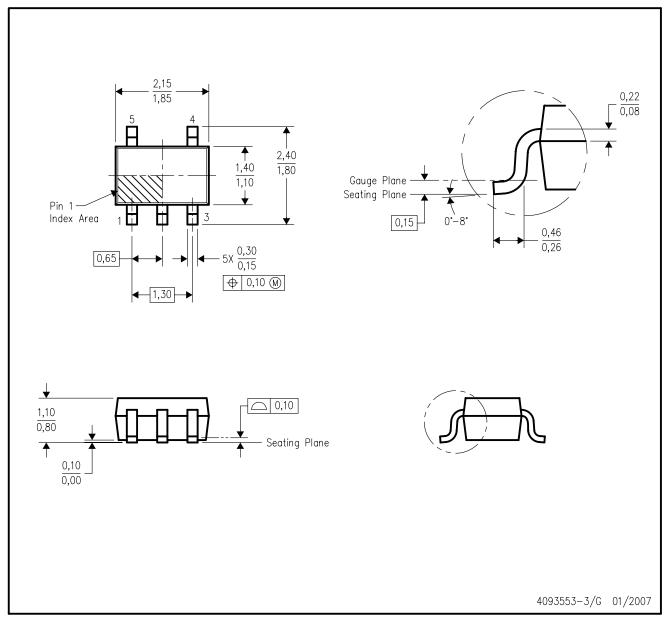
• Catalog: SN74AHC1G00

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

## DCK (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



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